AMENDMENTS TO THE CLAIMS

Claim 1. (canceled)

2. (previously presented) The imaging device of claim 7, wherein said photosensitive elements are arranged in a two-dimensional array.

3. (previously presented) The imaging device of claim 7, wherein said transparent material includes injection molded epoxy resin.

4. (previously presented) The imaging device of claim 7, further comprising leads connected to said semiconductor imaging chip, said leads being partially encapsulated in said transparent material.

Claims 5-6. (canceled)

7. (currently amended) An imaging device, comprising:

a frame having a support structure;

a semiconductor imaging chip supported by said support structure, said semiconductor imaging chip having an array of photosensitive elements configured to receive an image and generate a plurality of corresponding image signals; and

a package comprising a transparent material encapsulating said frame, support structure, and semiconductor imaging chip ~~in a transparent material~~, said transparent material covering said chip, said photosensitive elements receiving said image through said transparent material;

wherein ~~at least a portion~~ portions of said transparent material ~~supported in line with an image being received by~~ through which light passes to said photosensitive elements ~~of said semiconductor imaging chip is tinted~~ have respective color tints to provide colored light filtering.

8. (previously presented) The imaging device of claim 7, further comprising an optical light transmitting device, wherein said optical light transmitting device is formed of said transparent material.

9. (previously presented) The imaging device of claim 8 wherein said optical light transmitting device is a lens, said lens being formed of said transparent material.

10. (previously presented) The imaging device of claim 7, further comprising a color filter array molded into and encased by said transparent material.

11. (currently amended) An imaging system, comprising:

a transmitting system for transmitting an image including an image source, said transmitting system being arranged to transmit the entire image simultaneously onto each of a plurality of imaging devices;

wherein each of said plurality of imaging devices includes a semiconductor device including an array of photosensitive elements, each semiconductor device being mounted on a respective frame, each of said frames having a support structure, each of said semiconductor devices receiving said image and generating corresponding signals; and

wherein each said frame, support structure, and respective semiconductor device is encapsulated in a transparent material of a respective package for protecting

and supporting each said semiconductor device, ~~each of said packages being formed of transparent material,~~ said transparent material including injection molded resin for ~~transmitting~~ allowing the image from said image source ~~onto~~ to pass to said semiconductor devices, said transparent material of at least one of said packages having a color different from remaining packages.

12. (original) The system of claim 11, wherein said image source includes a lens.

13. (previously presented) The system of claim 11 wherein said semiconductor imaging devices include complementary color filters.

14. (previously presented) The system of claim 13, wherein said complementary color filters are molded into said packages.

15. (previously presented) The system of claim 13, wherein said packages include red, green and blue filters.

16. (previously presented) The system of claim 13, wherein said packages include cyan, magenta and yellow filters.

Claims 17-27. (canceled)

28. (currently amended) An imaging device, comprising:

a rigid housing having a cavity defined by side walls and a closed bottom ~~surface~~;

a semiconductor imaging chip located within said cavity of said housing, said semiconductor imaging chip including an array of photosensitive elements configured

to receive an image and generate corresponding signals, said photosensitive elements being covered by a transparent cover;

said semiconductor imaging chip being encapsulated in a transparent material, wherein said transparent material is disposed within said cavity and is contained by said side walls and closed bottom of said housing; and

an optical light transmitting device ~~supported in line with~~ by way of light from an image ~~being received by~~ passes to said photosensitive elements.

29. (previously presented) The device of claim 28, wherein said transparent cover includes a color filter.

Claim 30. (canceled)

31. (previously presented) The imaging device of claim 28, wherein said housing is formed of molded plastic.

32. (previously presented) The imaging device of claim 7, wherein said optical light transmitting device is a lens, said lens being formed of said transparent material.

33. (previously presented) The imaging device of claim 28, wherein said housing is formed of a ceramic material.

34. (previously presented) The imaging device of claim 7, wherein said optical light transmitting device is a color filter, said color filter being supported separate from said package of said transparent material.

35. (previously presented) The imaging device of claim 28, wherein said transparent material has an uppermost surface substantially planar to an uppermost surface of said sidewalls of said housing.